

# Peter Filipp Fuchs

## List of Publications by Year in descending order

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31  
papers

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citations

933447

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31  
docs citations

31  
times ranked

215  
citing authors

#	ARTICLE	IF	CITATIONS
1	Mechanical behavior of 3D-printed polymeric metamaterials for lightweight applications. Journal of Applied Polymer Science, 2022, 139, 51618.	2.6	15
2	Matrix-fiber interfacial debonding in soft composite materials: Cyclically behavior modeling and microstructural evolution. Composites Part B: Engineering, 2022, 237, 109853.	12.0	3
3	Towards electro-thermo-mechanical lifetime assessment for arbitrary power electronics. Microelectronics Reliability, 2022, 133, 114537.	1.7	2
4	A Review on Modeling Cure Kinetics and Mechanisms of Photopolymerization. Polymers, 2022, 14, 2074.	4.5	33
5	Asymmetric chiral and antichiral mechanical metamaterials with tunable Poisson's ratio. APL Materials, 2022, 10, .	5.1	9
6	Investigation of adhesion properties in load coupling applications for flexible composites. Materials Today: Proceedings, 2021, 34, 41-46.	1.8	7
7	The contribution of mechanical interactions to the constitutive modeling of fiber-reinforced elastomers. European Journal of Mechanics, A/Solids, 2021, 85, 104081.	3.7	15
8	Elastic load coupling with tailored elastomer composites. Composites Part C: Open Access, 2021, 4, 100088.	3.2	0
9	Quantifying matrix-fiber mechanical interactions in hyperelastic materials. International Journal of Mechanical Sciences, 2021, 195, 106268.	6.7	2
10	Functional mechanical metamaterial with independently tunable stiffness in the three spatial directions. Materials Today Advances, 2021, 11, 100155.	5.2	12
11	Analysis of the critical stresses in high-voltage composite winding insulations under thermal loads. Journal of Composite Materials, 2020, 54, 2073-2084.	2.4	0
12	Influence of Fiber Orientation and Adhesion Properties On Tailored Fiber-reinforced Elastomers. Applied Composite Materials, 2020, 27, 149-164.	2.5	12
13	Comparison and Impact of Different Fiber Debond Techniques on Fiber Reinforced Flexible Composites. Polymers, 2020, 12, 472.	4.5	13
14	Fracture mechanical characterization of mica-filled epoxy glass composites under monotonic and cyclic loading. Journal of Composite Materials, 2019, 53, 741-751.	2.4	3
15	Comparison of steady-state and transient thermal conductivity testing methods using different industrial rubber compounds. Polymer Testing, 2019, 80, 106121.	4.8	34
16	A Sequential Finite Volume Method / Finite Element Analysis of a Power Electronic Semiconductor Chip., 2019, , .		1
17	Numerical Analysis of the Influence of Polymeric Materials on a MEMS Package Performance Under Humidity and Temperature Loads. , 2019, , .		3
18	Model free kinetics coupled with finite element method for curing simulation of thermosetting epoxy resins. Journal of Applied Polymer Science, 2018, 135, 46408.	2.6	10

#	ARTICLE	IF	CITATIONS
19	Heat Dissipation in Epoxy/Amine-Based Gradient Composites with Alumina Particles: A Critical Evaluation of Thermal Conductivity Measurements. <i>Polymers</i> , 2018, 10, 1131.	4.5	15
20	Evaluation of Digital Image Correlation Techniques for the Determination of Coefficients of Thermal Expansion for Thin Reinforced Polymers.. , 2018, , .		2
21	Influence of environmental factors like temperature and humidity on MEMS packaging materials. , 2018, , .		3
22	Modeling of manufacturing induced residual stresses of viscoelastic epoxy mold compound encapsulations. , 2017, , .		5
23	Finite element analysis of arbitrarily complex electronic devices. , 2016, , .		7
24	Numerical simulation of the electrical performance of printed circuit boards under cyclic thermal loads. <i>Microelectronics Reliability</i> , 2016, 62, 148-155.	1.7	5
25	Cyclic mechanical behavior of thin layers of copper: A theoretical and numerical study. <i>Journal of Strain Analysis for Engineering Design</i> , 2016, 51, 161-169.	1.8	5
26	Method development for the cyclic characterization of thin copper layers for PCB applications. <i>Circuit World</i> , 2014, 40, 53-60.	0.9	8
27	Local damage simulations of printed circuit boards based on inâ€plane cohesive zone parameters. <i>Circuit World</i> , 2013, 39, 60-66.	0.9	6
28	PCB drop test lifetime assessment based on simulations and cyclic bend tests. <i>Microelectronics Reliability</i> , 2013, 53, 774-781.	1.7	11
29	Determination of the orthotropic material properties of individual layers of printed circuit boards. <i>Microelectronics Reliability</i> , 2012, 52, 2723-2730.	1.7	26
30	Experimental Determination of Cohesive Zone Models for Epoxy Composites. <i>Experimental Mechanics</i> , 2011, 51, 779-786.	2.0	19
31	Cyclic bend tests for the reliability evaluation of printed circuit boards under dynamic loads. <i>Frattura Ed Integrita Strutturale</i> , 2011, 5, 64-73.	0.9	3